

# QUALIFICATIONS PACK - OCCUPATIONAL STANDARDS FOR TELECOM INDUSTRY



## Contents

1. Introduction and Contacts.....	1
2. Qualifications Pack.....	2
3. Glossary of Key Terms.....	3
4. OS Units.....	5
5. Annexure: Nomenclature for QP & OS.....	26
6. Assessment Criteria .....	28

### What are Occupational Standards(OS)?

- OS describe what individuals need to do, know and understand in order to carry out a particular job role or function
- OS are performance standards that individuals must achieve when carrying out functions in the workplace, together with specifications of the underpinning knowledge and understanding

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## Introduction

### Qualifications Pack - Telecom Surface Mount Technology (SMT) Technician

**SECTOR:** TELECOM

**SUB-SECTOR:** Handset

**OCCUPATION:** Communication Electronics

**REFERENCE ID:** TEL/Q2501

**ALIGNED TO:** NCO – 2015/Nil

**Brief Job Description:** Telecom SMT Technician is responsible for handling end-to-end SMT process. Core functionality includes, screen printing, component placement, reflow soldering, cleaning and inspection, including re-work to address defects. The technician will be handling high end machinery/equipment towards achieving the above functionality.

**Personal Attributes:** This job requires the individual to have technical appreciation of the processes, analytical skills, eye for details and work towards optimal throughput. Individual needs to be focused, process oriented and should have ability to work with concentration during the shift hours.

*Qualification Pack for Telecom Surface Mount Technology (SMT) Technician*

<b>Job Details</b>	<b>Qualifications Pack Code</b>	<b>TEL/Q2501</b>		
	<b>Job Role</b>	<b>Telecom Surface Mount Technology Technician</b>		
	<b>Credits(NSQF)</b>	<b>TBD</b>	<b>Version number</b>	<b>1.0</b>
	<b>Sector</b>	<b>Telecom</b>	<b>Drafted on</b>	<b>14/06/2017</b>
	<b>Sub-sector</b>	<b>Handset</b>	<b>Last reviewed on</b>	<b>10/11/2017</b>
	<b>Occupation</b>	<b>Communication Electronics</b>	<b>Next review date</b>	<b>10/11/2021</b>
	<b>NSQF Clearance on</b>	<b>DD/MM/YYYY</b>		

<b>Job Role</b>	<b>Telecom Surface Mount Technology Technician</b>
<b>Role Description</b>	Telecom SMT Technician handles all stages of SMT production line processes, including QA and re-work to address defects.
<b>NSQF level</b>	4
<b>Minimum Educational Qualifications*</b>	ITI
<b>Maximum Educational Qualifications*</b>	NA
<b>Minimum Job Entry Age</b>	18 Years
<b>Experience</b>	NIL
<b>Applicable National Occupational Standards (NOS)</b>	<b>Compulsory:</b> <ol style="list-style-type: none"> <li>1. <a href="#">TEL/N2503 (Screen printing of telecom boards)</a></li> <li>2. <a href="#">TEL/N2504 (Component placement on telecom boards)</a></li> <li>3. <a href="#">TEL/N2505 (Re-flow soldering on telecom boards)</a></li> <li>4. <a href="#">TEL/N2502 (Cleaning and inspection of telecom boards)</a></li> <li>5. <a href="#">TEL/N2509 (Health and safety)</a></li> </ol>
<b>Performance Criteria</b>	As described in the relevant OS units

*Qualification Pack for Telecom Surface Mount Technology (SMT) Technician*

Keywords/ Terms	Description
<b>Definitions</b>	<b>Sector</b> Sector is a conglomeration of different business operations having similar businesses and interests. It may also be defined as a distinct subset of the economy whose components share similar characteristics and interests.
<b>Sub-sector</b>	Sub-sector is derived from a further breakdown based on characteristics and interests of its components.
<b>Occupation</b>	Occupation is a set of job roles, which perform similar/ related set of functions in an industry.
<b>Function</b>	Function is an activity necessary for achieving the key purpose of the sector, occupation, or area of work, which can be carried out by a person or a group of persons. Functions are identified through functional analysis and form the basis of OS.
<b>Job Role</b>	Job role defines a unique set of functions that together form a unique employment opportunity in an organization.
<b>OS</b>	OS specify the standards of performance an individual must achieve when carrying out a function in the workplace, together with the knowledge and understanding they need to meet that standard consistently. Occupational Standards are applicable both in the Indian and global contexts.
<b>Performance Criteria</b>	Performance Criteria are statements that together specify the standard of performance required when carrying out a task.
<b>NOS</b>	NOS are Occupational Standards which apply uniquely in the Indian context.
<b>Qualifications Pack Code</b>	Qualifications Pack Code is a unique reference code that identifies a qualifications pack.
<b>Qualifications Pack</b>	Qualifications Pack comprises the set of OSs, together with the educational, training and other criteria required to perform a job role. A Qualifications Pack is assigned a unique qualification pack code.
<b>Unit Code</b>	Unit Code is a unique identifier for an Occupational Standard, which is denoted by an 'N'.
<b>Unit Title</b>	Unit Title gives a clear overall statement about what the incumbent should be able to do.
<b>Description</b>	Description gives a short summary of the unit content. This would be helpful to anyone searching on a database to verify that this is the appropriate OS, they are looking for.
<b>Knowledge and Understanding</b>	Knowledge and Understanding are statements which together specify the technical, generic, professional and organizational specific knowledge that an individual need in order to perform to the required standard.
<b>Organizational Context</b>	Organizational Context includes the way the organization is structured and how it operates, including the extent of operative knowledge managers have of their relevant areas of responsibility.
<b>Technical Knowledge</b>	Technical Knowledge is the specific knowledge needed to accomplish specific designated responsibilities.
<b>Core Skills or Generic Skills</b>	Core Skills or Generic Skills are a group of skills that are key to learning and working in today's world. These skills are typically needed in any work environment. In the context of the OS, these include communication related skills that are applicable to most job roles.

*Qualification Pack for Telecom Surface Mount Technology (SMT) Technician*

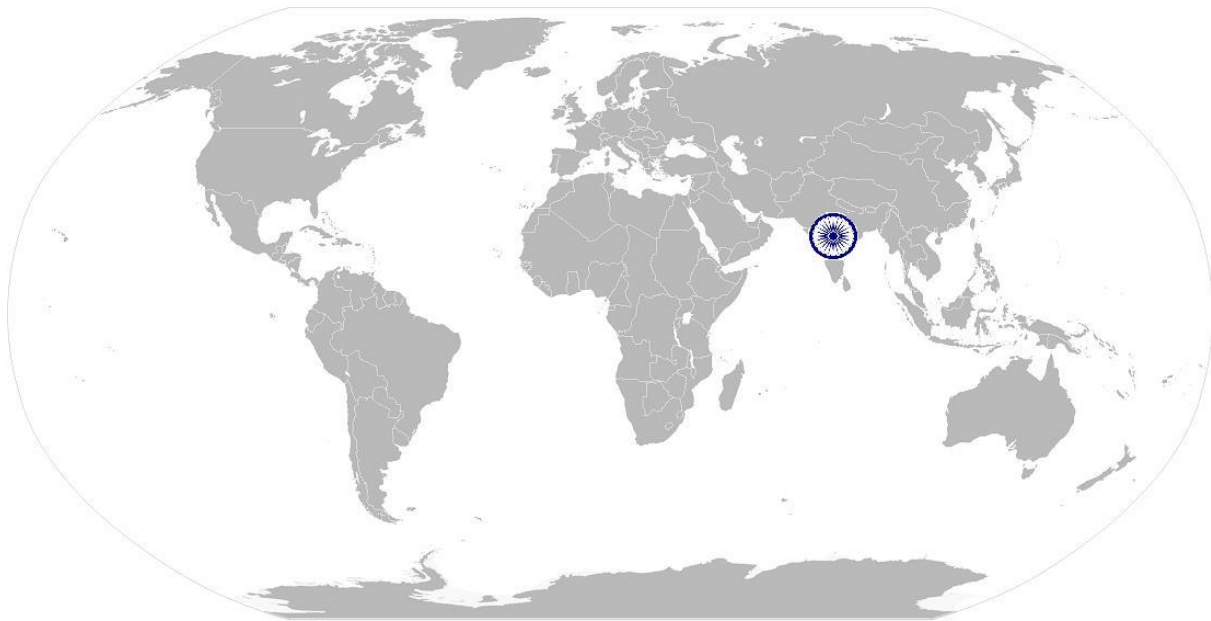
Acronym	Keywords/ Terms	Description
	SMT	Surface Mount Technology
	BGA	Ball Grid Array
	PCB	Printed Circuit Board
	ICs	Integrated Circuits
	MSDS	Material Safety Data Sheet
	ESD	Electrostatic discharge
	QA	Quality Assurance
	QC	Quality Checks

TEL/N2503

Screen printing of telecom boards

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# National Occupational Standard



## Overview

This unit is about the screen printing process of telecom boards and the associated preparatory activities.

**TEL/N2503**

**Screen printing of telecom boards**

<b>National Occupational Standard</b>	<b>Unit Code</b>	TEL/N2503
	<b>Unit Title (Task)</b>	Screen printing of telecom boards
	<b>Description</b>	This unit is screen printing of telecom boards and associated processes with the aim to achieve uniform deposition of solder paste on the required positions on the boards.
	<b>Scope</b>	This unit/ task covers the following: <ul style="list-style-type: none"> <li>• Baking of boards</li> <li>• Screen printing process</li> </ul>
	<b>Performance Criteria (PC) w.r.t. the Scope</b>	
	<b>Element</b>	<b>Performance Criteria</b>
	<b>Baking of boards</b>	To be competent, the user/ individual on the job must be able to: <ul style="list-style-type: none"> <li>PC1. ascertain the baking requirements as per the customer specifications or standard processes</li> <li>PC2. demonstrate proper stacking/ placement of boards in the oven rack</li> <li>PC3. demonstrate setting of temperature and timer of the oven as per the requirement</li> </ul>
	<b>Screen printing process</b>	To be competent, the user/ individual on the job must be able to: <ul style="list-style-type: none"> <li>PC4. identify and select correct tools and accessories (stencil matching the part/ pattern number vis-à-vis the PCB for screen printing, squeeze as per PCB size, correct solder paste/ combination as per the specifications)</li> <li>PC5. demonstrate proper cleaning of the stencil, before and after use, using the specified process and solvents</li> <li>PC6. demonstrate process for even deposition of paste on boards</li> <li>PC7. demonstrate process of properly thawing the solder pastes and setting of solder paste parameters as per the specifications</li> <li>PC8. demonstrate correct positioning of stencil, solder paste &amp; squeeze and related parameters in the screen printer and undertake screen printing operation</li> <li>PC9. carry out paste thickness measurement as part of post printing process and check the thickness for conformance to the specification</li> </ul>
	<b>Knowledge and Understanding (K)</b>	
	<b>A. Organizational Context</b> (Knowledge of the company / organization and its processes)	The user/ individual on the job needs to know and understand: <ul style="list-style-type: none"> <li>KA1. process and procedures for drawing stores, drawings, specification and their safe keeping</li> <li>KA2. risk and impact of not following defined procedures/ work instructions and timelines.</li> <li>KA3. escalation matrix for reporting identified incidents, troubles and/ or emergencies</li> <li>KA4. records to be maintained and implications of non-maintenance of the same</li> <li>KA5. SHE and OHS guidelines and regulations as per company's norms</li> </ul>
<b>B. Technical knowledge</b>	The user/ individual on the job needs to know and understand: <ul style="list-style-type: none"> <li>KB1. impact of moisture on PCBs and relevance of baking</li> <li>KB2. importance of selecting soldering paste with desired characteristics</li> <li>KB3. relevance of proper thawing of soldering paste, cleaning of stencils and even application of soldering paste on the PCB</li> <li>KB4. impact of temperature and humidity on the process</li> <li>KB5. impact of proper alignment and supporting of screen by proper locating of support pins</li> <li>KB6. operation of screen printing machine</li> </ul>	

**TEL/N2503**

**Screen printing of telecom boards**

	KB7. importance of proper stowage of consumables KB8. quality requirements of PCBs like warpage issues/ fiducial mark availability etc.
<b>Skills (S) [Optional]</b>	
<b>A. Core Skills/ Generic Skills</b>	<b>Writing Skills</b>
	Not applicable
	<b>Reading Skills</b>
	The user/individual on the job needs to know and understand how to: SA1. read technical literature/ parameters SA2. read and comprehend part/ pattern/ drawing numbers SA3. read and comprehend parameters as per the project report/ chart SA4. read and understand manuals, requirement documents, health and safety instructions, memos, reports etc.
	<b>Oral Communication (Listening and speaking skills)</b>
	The user/individual on the job needs to know and understand how to: SA5. communicate with colleagues, peers and supervisor SA6. liaising and co-ordination skills
<b>B. Professional skills</b>	<b>Decision Making</b>
	Not applicable
	<b>Plan and Organize</b>
	The user/ individual on the job needs to know and understand how to: SB1. set-up the screen printing environment SB2. ensure proper handling of all consumables SB3. establish and undertake sequential flow of all activities leading to screen printing SB4. undertake sample checks to ensure QA compliance SB5. take decision on re-work, if required SB6. read and comprehend/ understand equipment operations manual SB7. interpret screening requirements from user specifications SB8. achieve proper application of soldering paste conforming to thickness and other properties/ specifications SB9. properly handle the components during operations and post completion processing/ storage
	<b>Customer Centricity</b>
	Not applicable
	<b>Problem Solving</b>
	Not applicable
	<b>Analytical Thinking</b>
	Not applicable
	<b>Critical Thinking</b>
	Not applicable

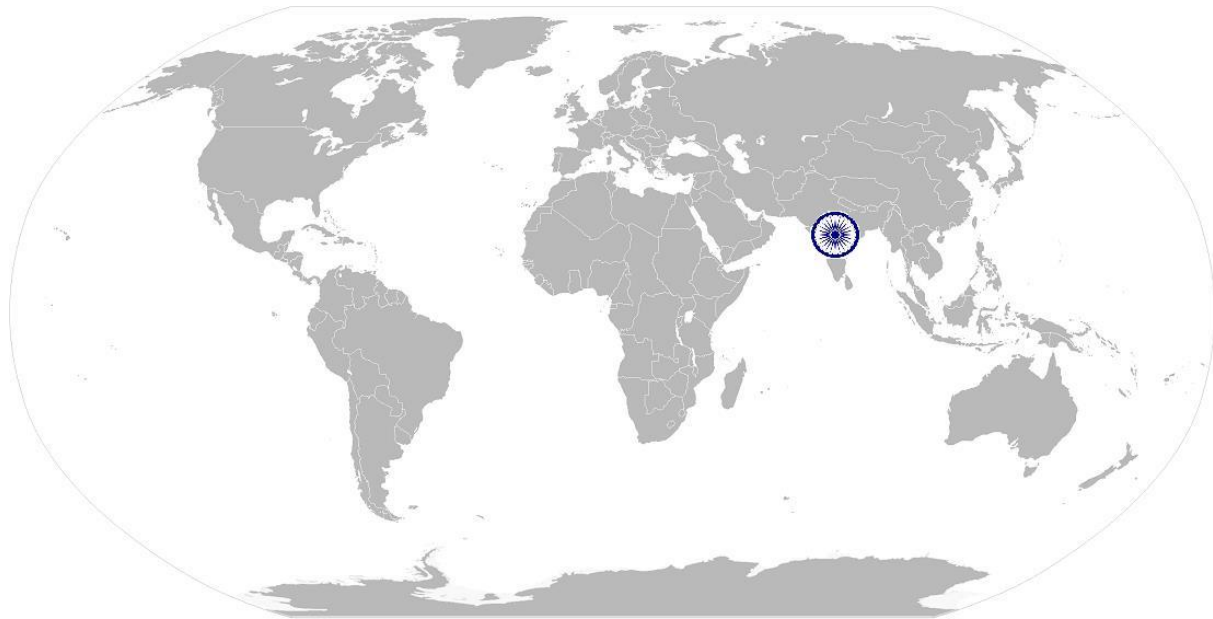


**TEL/N2503**

**Screen printing of telecom boards**

## **NOS Version Control**

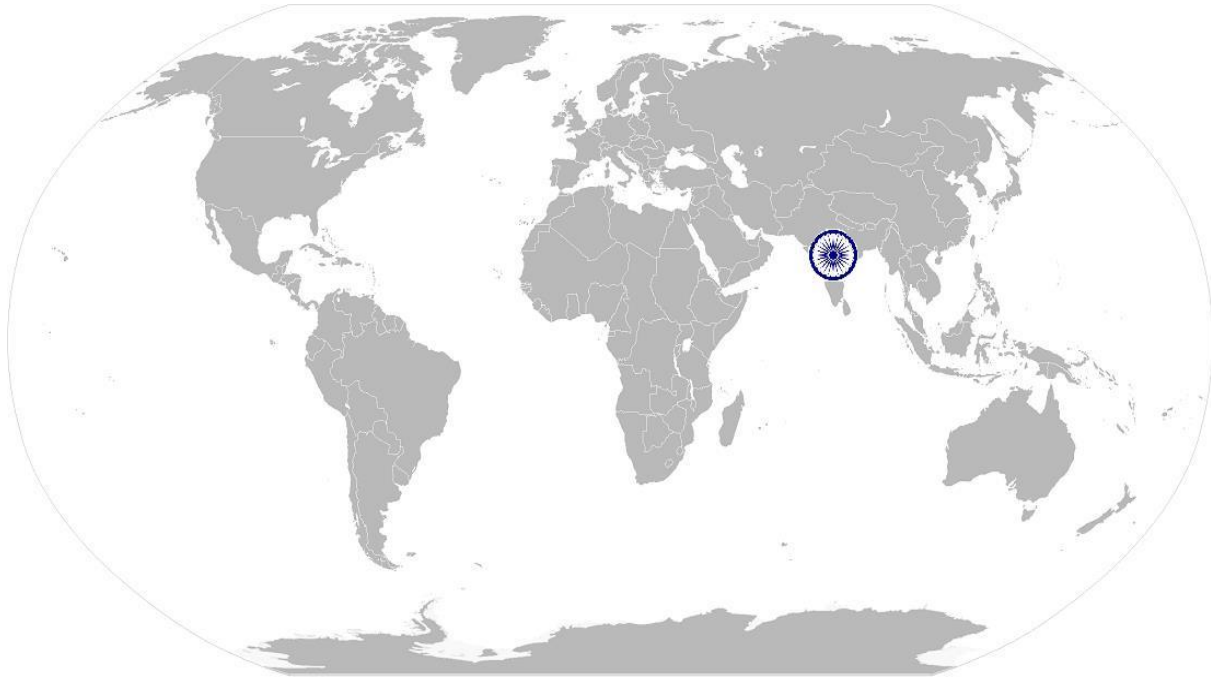
<b>NOS Code</b>	<b>TEL/N2503</b>		
<b>Credits (NSQF)</b>	<b>TBD</b>	<b>Version number</b>	<b>1.0</b>
<b>Industry</b>	<b>Telecom</b>	<b>Drafted on</b>	<b>14/06/2017</b>
<b>Industry Sub-sector</b>	<b>Handset</b>	<b>Last reviewed on</b>	<b>10/11/2017</b>
<b>Occupation</b>	<b>Communication Electronics</b>	<b>Next review date</b>	<b>10/11/2021</b>





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# National Occupational Standard



## Overview

This unit is about component placement on telecom boards using chip shooter and fine pitch placer equipment.

**TEL/N2504**

**Component placement on telecom boards**

<b>National Occupational Standard</b>	<b>Unit Code</b>	<b>TEL/N2504</b>
	<b>Unit Title (Task)</b>	<b>Component placement on telecom boards</b>
	<b>Description</b>	This unit is screen printing of boards and associated processes with the aim to achieve uniform deposition of solder paste on the required positions of components on the board using chip shooter and pitch placer equipment.
	<b>Scope</b>	This unit/ task covers the following: <ul style="list-style-type: none"> <li>• Feeding placement data</li> <li>• Loading of chip-component rolls</li> <li>• Loading of chip component trays</li> <li>• Operating chip shooter and fine pitch placer and functional/ QA checks on the PCB</li> </ul>
	<b>Performance Criteria (PC) w.r.t. the Scope</b>	
	<b>Element</b>	<b>Performance Criteria</b>
	<b>Feeding placement data</b>	To be competent, the user/ individual on the job must be able to: <p>PC1. read specifications of board and map to the correct software version of chip shooter/ pitch placer</p> <p>PC2. read and interpret Gerber data, x-y coordinate data</p> <p>PC3. work with user interface and features of the machine/ equipment software and demonstrate the same.</p> <p>PC4. demonstrate data entry/ loading of component placement program to the chip shooter/ fine pitch placer</p>
	<b>Loading of chip component rolls</b>	To be competent, the user/ individual on the job must be able to: <p>PC5. check operation of the roll feeder mechanism</p> <p>PC6. feed Gerber data and insert feeder rolls on the suggested slots of the chip shooter</p> <p>PC7. verify component rolls as per the Part number/ work specification</p> <p>PC8. demonstrate loading of chip component rolls in the feeder</p> <p>PC9. feed X-Y co-ordinate date for correct positioning of components</p>
	<b>Loading of chip component trays</b>	To be competent, the user/individual on the job must be able to: <p>PC10. load components on the tray as per the placement program</p> <p>PC11. place the components with correct orientation in the feeder tray</p> <p>PC12. check operation of the mechanism including vision cameras</p>
	<b>Operating chip shooter and fine pitch placer and functional/ QA checks on the PCB</b>	To be competent, the user/individual on the job must be able to: <p>PC13. verify correct loading of boards, program and component rolls/ trays</p> <p>PC14. check placement vacuum pressure</p> <p>PC15. check for feeder mechanism functions and ensure its error free operation</p> <p>PC16. operate the component placement equipment</p> <p>PC17. use tape board technique to verify the placement accuracy</p> <p>PC18. verify the correctness of components and placement (under microscope) for the first sample board</p>
<b>Knowledge and Understanding (K)</b>		

**TEL/N2504**

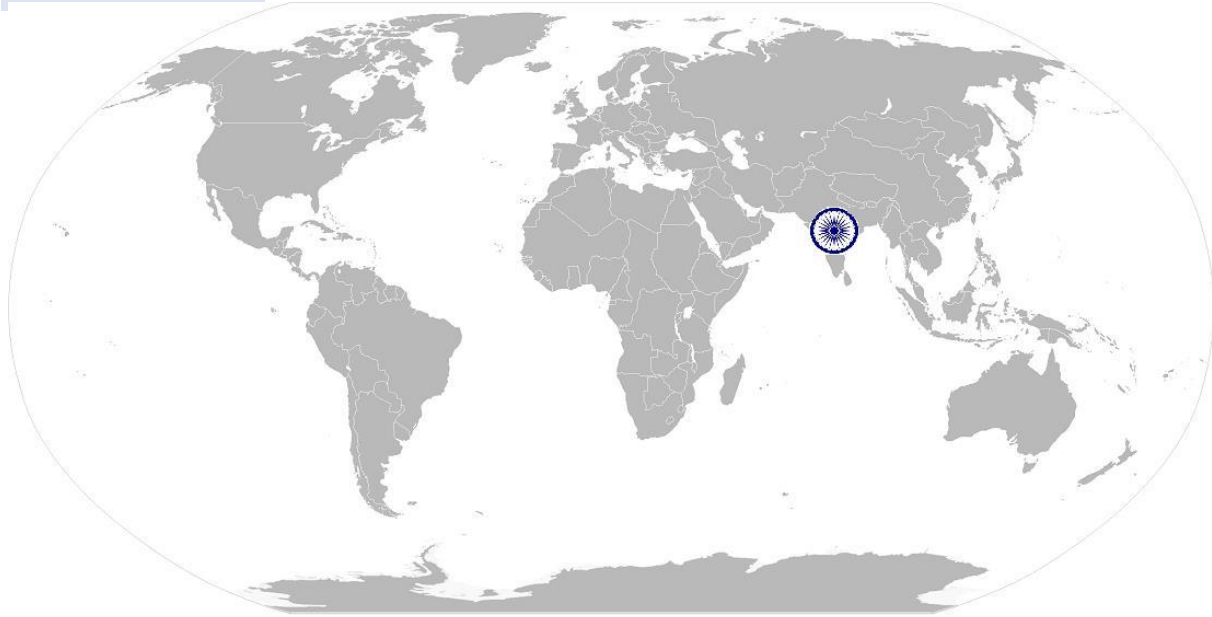
**Component placement on telecom boards**

<b>A. Organizational Context</b> (Knowledge of the company/ organization and its processes)	The user/ individual on the job needs to know and understand: KA1. work/project management concepts and applications KA2. procedure for drawing components/ drawings and impact of non-adherence to the procedures KA3. escalation matrix for reporting non-compliance KA4. process and work records to be maintained KA5. SHE and OHS guidelines and regulations as per company’s norms (precautions against solder fumes, basic electrical precautions)
<b>B. Technical knowledge</b>	The user/ individual on the job needs to know and understand: KB1. system specifications, part/ pattern numbers and Bill of Material KB2. operating parameters of component placement machines/ equipment KB3. understanding of Gerber and x-y co-ordinate data KB4. operations cycle of the component placement machine/ equipment KB5. reading/ verifying components under microscope to check correct placement and connectivity (no bend pins/ legs etc.) KB6. ESD precautions and hygiene KB7. type of SMT defects like tombstone and solder short
<b>Skill (s) [Optional]</b>	
<b>A. Core Skills/ Generic Skills</b>	<b>Writing Skills</b>
	The user/individual on the job needs to know and understand how to: SA1. technical writing (flow, process steps etc.)
	<b>Reading Skills</b>
	The user/individual on the job needs to know and understand how to: SA2. read work specifications, drawing and part/pattern numbers SA3. reading of technical literature/requirements SA4. technical writing (flow, process steps etc.) SA5. read and understand manuals, work orders, health and safety instructions, memos, reports etc.
	<b>Oral Communication (Listening and speaking skills)</b>
	The user/individual on the job needs to know and understand how to: SA6. communicate with colleagues, peers, management and stakeholders SA7. liaising and coordination skills
	<b>B. Professional skills</b>
	Not applicable
	<b>Plan and Organize</b>
	The user/ individual on the job needs to know and understand how to: SB1. sequence operations SB2. fulfil parameters for successful completion of each stage SB3. schedule work/ activities to comply to task time frame SB4. optimal programming skills required for machine/ equipment operation SB5. handling components tapes, tubes and trays SB6. checking operations of various machine components (feeder system, vacuum system, machine malfunction etc.)
	<b>Customer Centricity</b>
	Not applicable
	<b>Problem Solving</b>

**TEL/N2504**

**Component placement on telecom boards**

	Not applicable
	<b>Analytical Thinking</b>
	Not applicable
	<b>Critical Thinking</b>
	Not applicable

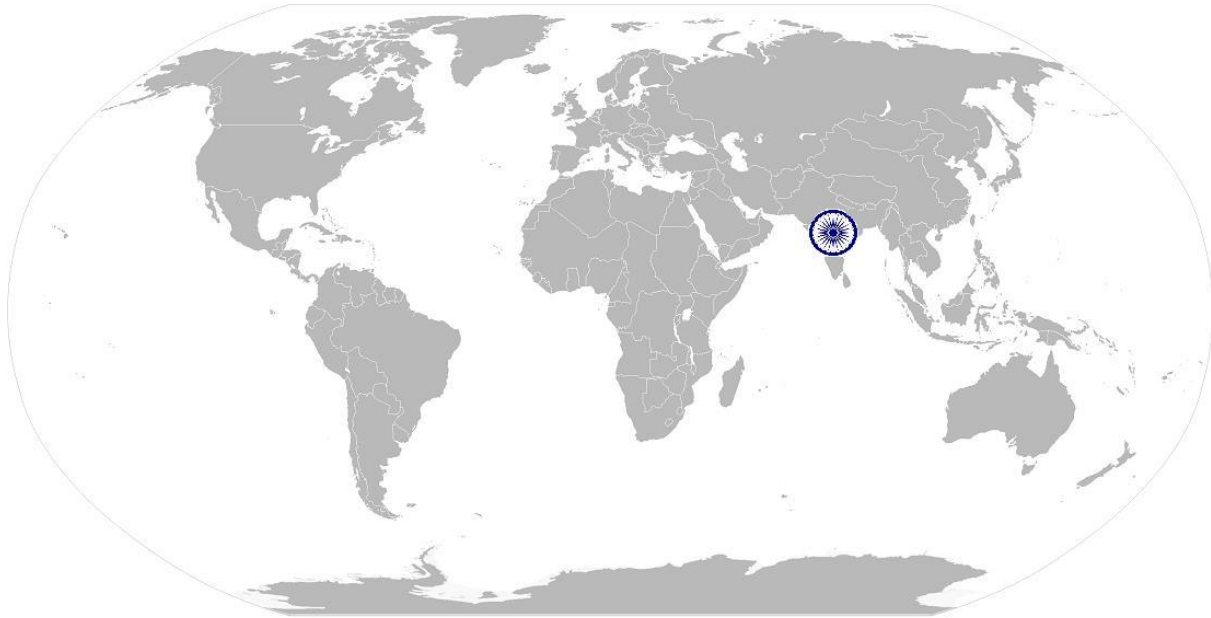


TEL/N2504

## Component placement on telecom boards

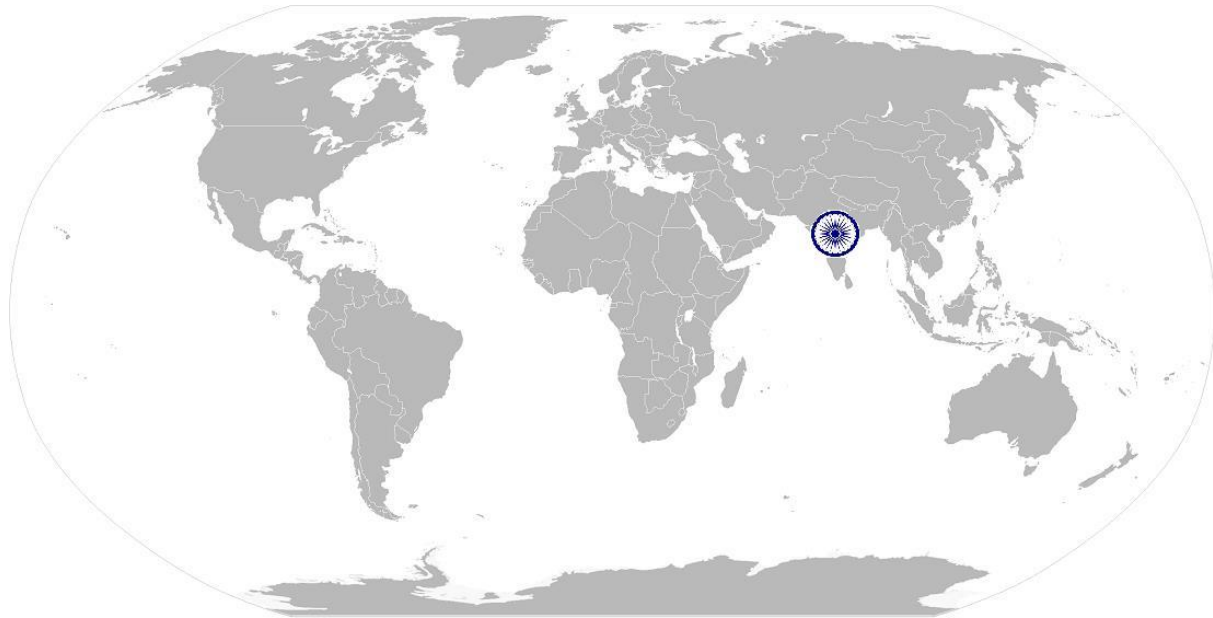
### NOS Version Control

<b>NOS Code</b>	<b>TEL/N2504</b>		
<b>Credits (NSQF)</b>	<b>TBD</b>	<b>Version number</b>	<b>1.0</b>
<b>Industry</b>	<b>Telecom</b>	<b>Drafted on</b>	<b>14/06/2017</b>
<b>Industry Sub-sector</b>	<b>Handset</b>	<b>Last reviewed on</b>	<b>10/11/2017</b>
<b>Occupation</b>	<b>Communication Electronics</b>	<b>Next review date</b>	<b>10/11/2021</b>



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# National Occupational Standard



## Overview

This unit is about undertaking re-flow soldering on telecom boards and all related processes.

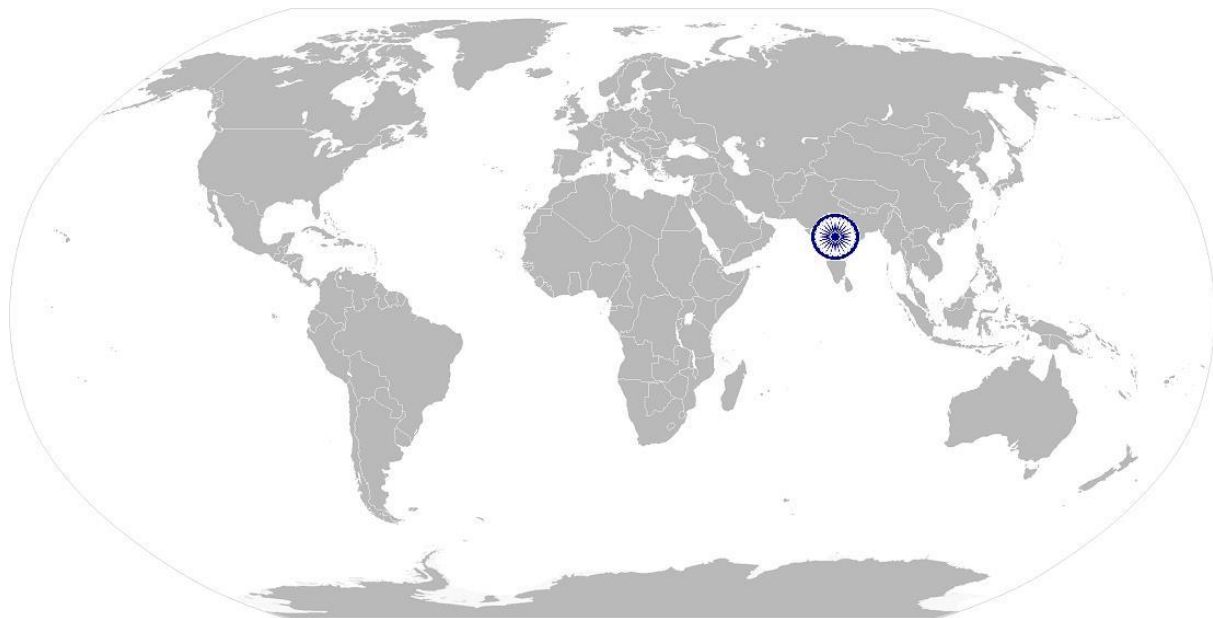
<b>National Occupational Standard</b>	<b>Unit Code</b>	TEL/N2505
	<b>Unit Title (Task)</b>	Reflow soldering on telecom boards
	<b>Description</b>	This unit is about re-flow soldering of telecom boards including all related processes and operations.
	<b>Scope</b>	This unit/ task covers the following: <ul style="list-style-type: none"> <li>• preparing the re-flow machine</li> <li>• re-flow operation on the PCB and its QA checks</li> </ul>
	<b>Performance Criteria (PC) w.r.t. the Scope</b>	
	<b>Element</b>	<b>Performance Criteria</b>
	<b>Preparing the re-flow machine</b>	To be competent, the user/ individual on the job must be able to: <ul style="list-style-type: none"> <li>PC1. interpret solder paste parameters from the datasheet and suggested parameters from re-flow machine</li> <li>PC2. demonstrate loading of parameters in the re-flow machine</li> <li>PC3. demonstrate passing a sample PCB through the re-flow machine, with reading being recorded using thermal probes</li> <li>PC4. match the readings with the desired outcome and undertake corrective settings</li> </ul>
	<b>Re-flow operation on the PCB and its QA checks</b>	To be competent, the user/ individual on the job must be able to: <ul style="list-style-type: none"> <li>PC5. undertake setting of machines is set as per the parameters as ascertained during the preparatory process</li> <li>PC6. prepare and pass the loaded PCB (with solder and components placed) through the re-flow machine</li> <li>PC7. safely remove the PCB at the end of the cycle</li> <li>PC8. check for any dry solder, ascertain even reflow, tombstone, de-lamination, misalignment and/ or disturbed components and any other damage to PCB</li> </ul>
	<b>Knowledge and Understanding (K)</b>	
	<b>A. Organizational context</b> (Knowledge of the company/ organization and its processes)	The user/ individual on the job needs to know and understand: <ul style="list-style-type: none"> <li>KA1. work/ project Management concepts and applications</li> <li>KA2. work instructions and operating guidelines for reflow machines/ processes and impact of non-adherence to the defined processes</li> <li>KA3. escalation matrix for reporting an incident</li> <li>KA4. records to be maintained and implications of non-maintenance of the same</li> <li>KA5. SHE and OHS guidelines and regulations as per company's norms</li> </ul>
<b>B. Technical Knowledge</b>	The user/individual on the job needs to know and understand: <ul style="list-style-type: none"> <li>KB1. solder characteristic at various temperature points</li> <li>KB2. effect of non-compliance of solder characteristic on the PCB performance</li> <li>KB3. setting of re-flow machine chamber temperature and PCB carrying belt speed to meet the desired characteristic.</li> <li>KB4. effects of dry-solder, cracked joints, voids, uneven reflow and delamination of PCB</li> </ul>	



Skill (s) [Optional]	
<b>A. Core Skills/ Generic Skills</b>	<b>Writing Skills</b>
	The user/individual on the job needs to know and understand how to: SA1. record performance/ test results SA2. maintain proper records as per given format
	<b>Reading Skills</b>
	The user/individual on the job needs to know and understand how to: SA3. read and understand technical documentation
	<b>Oral Communication (Listening and speaking skills)</b>
The user/individual on the job needs to know and understand how to: SA4. communicate with stakeholders SA5. liaison and coordination skills	
<b>B. Professional Skills</b>	<b>Decision Making</b>
	Not applicable
	<b>Plan and Organize</b>
	The user/individual on the job needs to know and understand how to: SB1. setup re-flow process environment SB2. setup test PCB with thermal sensors for recording parameters SB3. analyze results and undertake corrective setting SB4. read, understand and set-up solder parameters for re-flow process SB5. design and conduct test re-flow run SB6. obtain test results for analysis and corrective action SB7. technical appreciation of characteristic charts and performance curves
	<b>Customer Centricity</b>
	Not applicable
	<b>Problem Solving</b>
	Not applicable
	<b>Analytical Thinking</b>
	Not applicable
	<b>Critical Thinking</b>
Not applicable	

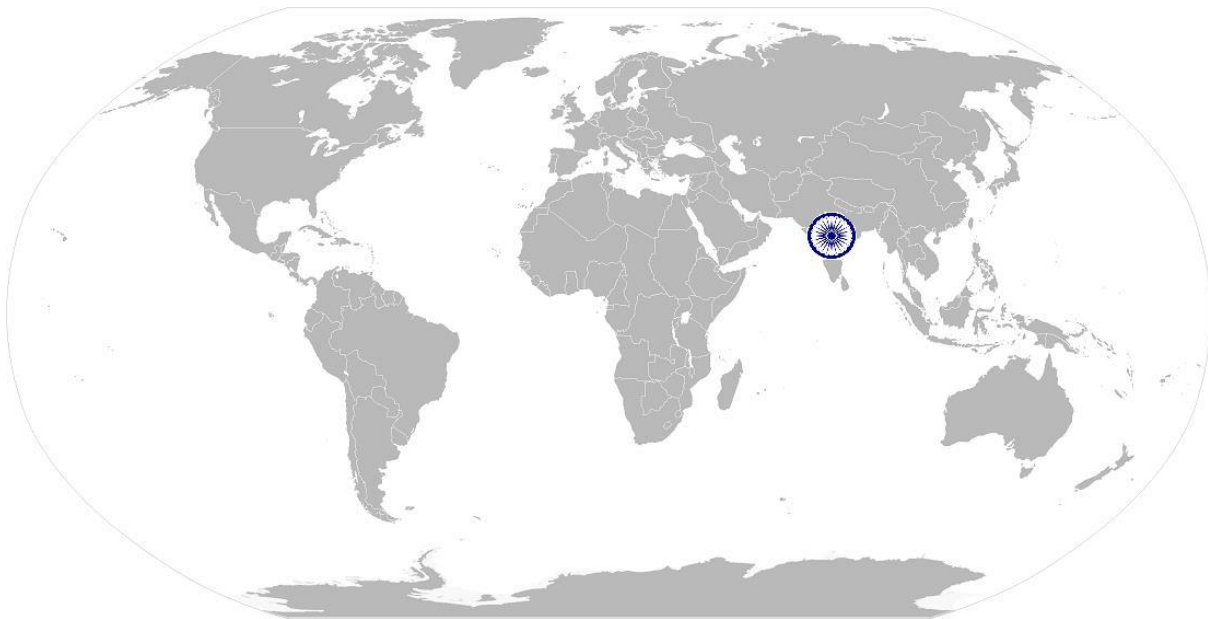
## **NOS Version Control**

NOS Code	TEL/N2505		
Credits (NSQF)	TBD	Version number	1.0
Industry	Telecom	Drafted on	14/06/2017
Industry Sub-sector	Handset	Last reviewed on	10/11/2017
Occupation	Communication Electronics	Next review date	10/11/2021



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# National Occupational Standard



## Overview

This unit is about cleaning and inspection of completed (with all components and soldering) telecom boards.

TEL/N2502

## Cleaning and inspection of telecom boards

National Occupational Standard

<b>Unit Code</b>	TEL/N2502
<b>Unit Title (Task)</b>	Cleaning and inspection of telecom boards
<b>Description</b>	This unit is about cleaning and inspection of completed telecom boards.
<b>Scope</b>	This unit/ task covers the following: <ul style="list-style-type: none"> <li>• Cleaning of telecom boards</li> <li>• Inspection – quality checks and assurance</li> </ul>
<b>Performance Criteria (PC) w.r.t. the Scope</b>	
<b>Element</b>	<b>Performance Criteria</b>
<b>Cleaning of telecom boards</b>	To be competent, the user/ individual on the job must be able to: PC1. demonstrate ability to clean the board from flux residues, white patches and/or powder, using correct and specified solvent PC2. operate vapor de-greaser (boil, rinse, vaporize and dry) to clean the boards PC3. demonstrate safe packaging and storage of telecom boards, using the specified wrapping material
<b>Inspection – quality checks and assurance</b>	To be competent, the user/individual on the job must be able to: PC4. demonstrate ability to check telecom boards for any missing components, wrongly mounted components (location, value) or improper placement, vis-à-vis the specifications PC5. demonstrate ability to check the telecom boards for soldering workmanship and defects, proper placement of board identifier, adherence to specifications, conformal coatings PC6. demonstrate complaint handling and escalation processes PC7. undertake checks of shop floor with respect to adherence to the processes and parameters (temperature, humidity)
<b>Knowledge and Understanding (K)</b>	
<b>A. Organizational context</b> (Knowledge of the company/ organization and its process relevant to area of responsibilities)	The user/individual on the job needs to know and understand: KA1. work/ project management concepts and applications KA2. risk and impact of not following defined procedures/ work instructions KA3. escalation matrix for reporting identified incidents, troubles and/ or emergencies e.g. system failures, fire and power failures KA4. records to be maintained and implications of non-maintenance of the same KA5. SHE and OHS guidelines and regulations as per company's norms
<b>B. Technical knowledge</b>	The user/ individual on the job needs to know and understand: KB1. use of cleaning chemicals/ solvents for PCBs KB2. process of cleaning KB3. use of vapor de-freezer equipment for PCB cleaning KB4. QA/QC parameters relating to the manual soldering KB5. IPC standards of soldering

TEL/N2502

### Cleaning and inspection of telecom boards

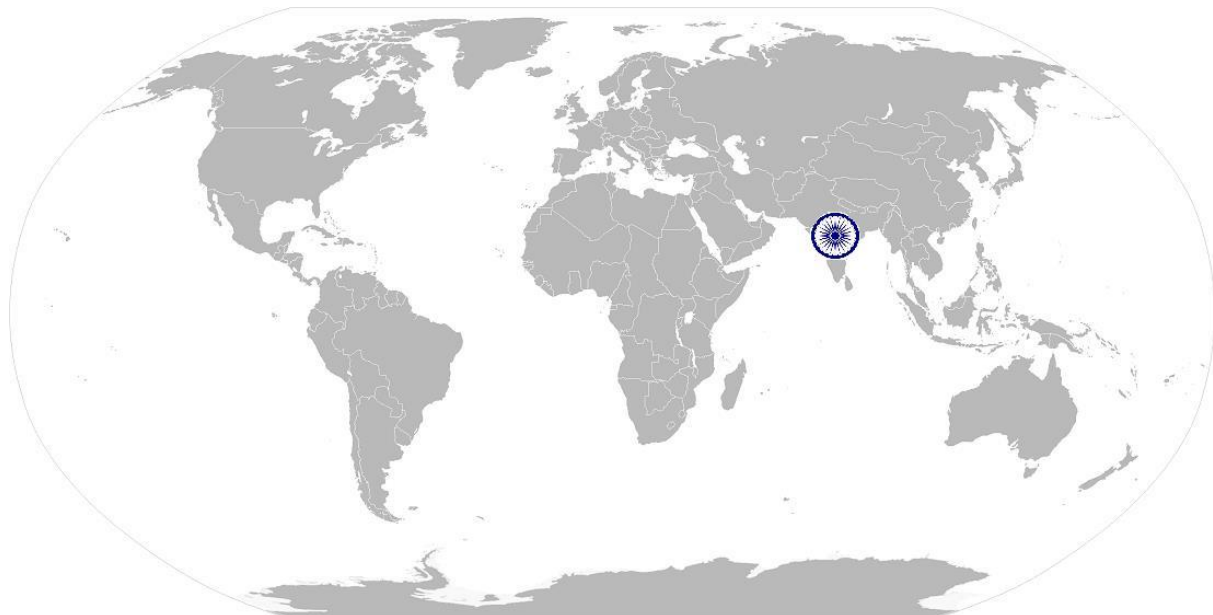
Skill (s) [Optional]	
	<b>Writing Skills</b>
<b>A. Core Skills/ Generic Skills</b>	The user/ individual on the job needs to know and understand how to:
	SA1. record performance/ test results
	SA2. maintain proper records as per given format
	<b>Reading Skills</b>
	The user/ individual on the job needs to know and understand and comprehend:
	SA3. work related technical documentation and drawings
SA4. process and guidelines to be followed	
<b>Oral Communication (Listening and speaking Skills)</b>	
<b>B. Professional skills</b>	The user/ individual on the job needs to know and understand how to:
	SA5. communicate with stakeholders (co-workers, superiors)
	SA6. liaison and co-ordinate with team members and supervisors
	<b>Decision Making</b>
	Not applicable
	<b>Plan and Organize</b>
<b>B. Professional skills</b>	The user/individual on the job needs to know and understand how to:
	SB1. setup PCB cleaning environment
	SB2. apply health and safety guidelines to PCB cleaning
	SB3. analyze QA/QC and undertake corrective setting
	SB4. undertake cleaning of PCBs
	SB5. ascertain parameters and operational characteristics of jigs, equipment and process parameters
	SB6. understand QA/QC parameters and implications of their non-adherence
	<b>Customer Centricity</b>
	Not applicable
	<b>Problem Solving</b>
	Not applicable
	<b>Analytical Thinking</b>
Not applicable	
<b>Critical Thinking</b>	
Not applicable	

TEL/N2502

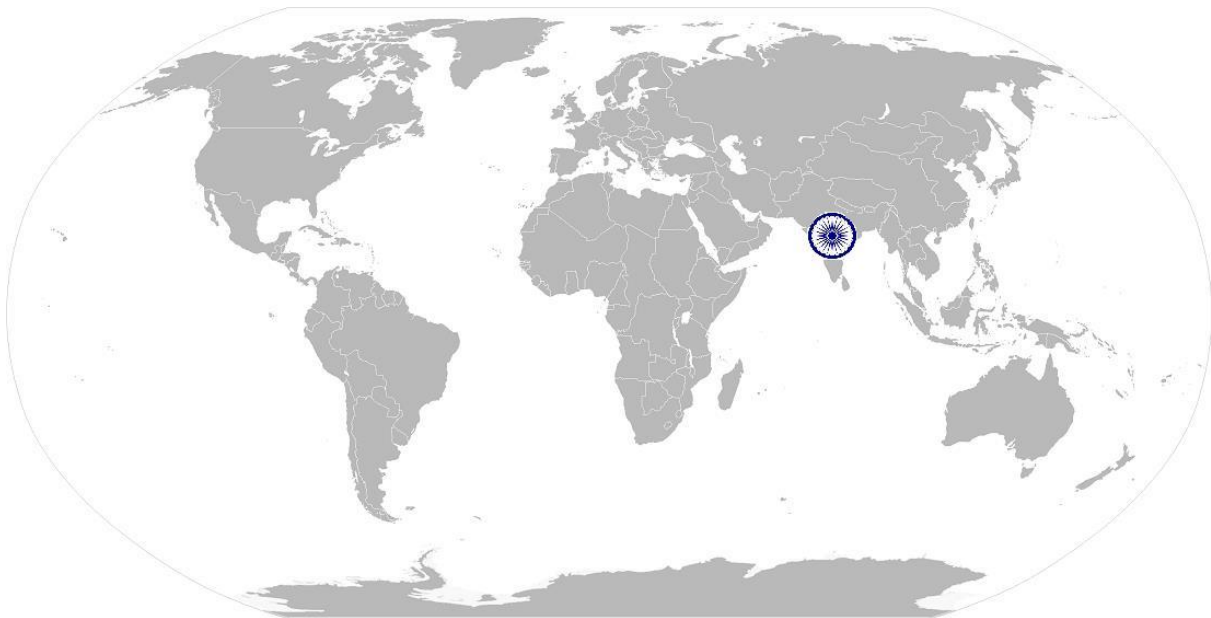
Cleaning and inspection of telecom boards

## NOS Version Control

<b>NOS Code</b>	<b>TEL/N2502</b>		
<b>Credits (NSQF)</b>	<b>TBD</b>	<b>Version number</b>	<b>1.0</b>
<b>Industry</b>	<b>Telecom</b>	<b>Drafted on</b>	<b>14/06/2017</b>
<b>Industry Sub-sector</b>	<b>Handset</b>	<b>Last reviewed on</b>	<b>10/11/2017</b>
<b>Occupation</b>	<b>Communication Electronics</b>	<b>Next review date</b>	<b>10/11/2021</b>



# National Occupational Standard



## Overview

This unit is about monitoring the working environment and making sure it meets requirements for health, safety and security.



TEL/N2509

## Health and Safety

National Occupational Standard	<b>Unit Code</b>	TEL/N2509
	<b>Unit Title (Task)</b>	Health and Safety
	<b>Description</b>	This unit is about monitoring the working environment and making sure it meets requirements for health, safety and security.
	<b>Scope</b>	This unit/ task covers the following: Health & Safety: Compliance and emergency procedures
	<b>Performance Criteria(PC) w.r.t. the Scope</b>	
	<b>Element</b>	<b>Performance Criteria</b>
	<b>Health &amp; Safety: Compliance and emergency procedures</b>	<p>To be competent, the user/individual on the job must be able to:</p> <p>PC1. ensure that work is carried out in accordance with the laid down safety, security policies and procedures of the organization</p> <p>PC2. ensure that site is assessed for safety and emergency readiness compliance as per company's guidelines</p> <p>PC3. ensure electrical safety compliances and EMI/ EMC hygiene requirements are met as per the guidelines</p> <p>PC4. identify and correct any hazards that you can deal with safely, competently and within the limits of your authority</p> <p>PC5. report any hazards that you are not competent to deal with to the relevant person in line with organizational procedures and warn other people who may be affected</p> <p>PC6. follow your organizations 's emergency procedures promptly, calmly and efficiently</p> <p>PC7. identify and recommend opportunities for improving health, safety, security to the designated person</p> <p>PC8. complete any health and safety records legibly and accurately</p>
	<b>Knowledge and Understanding (K)</b>	
	<b>A. Organizational Context</b> (Knowledge of the company / organization and its processes)	<p>The user/individual on the job needs to know and understand:</p> <p>KA1. legislative requirements and organizations procedures for health, safety and security and role and responsibilities in relation to this</p> <p>KA2. what is meant by hazard, including the different types of health and safety hazards that can be found in the workplace</p> <p>KA3. how and when to report hazards</p> <p>KA4. limits of your responsibility for dealing with hazards</p> <p>KA5. your organization's emergency procedures for different emergency situations and the importance of following these</p> <p>KA6. the importance of maintaining high standards of health, safety and security</p> <p>KA7. implications that any non – compliance with health, safety and security may have on individuals and the organization</p>

TEL/N2509

**Health and Safety**

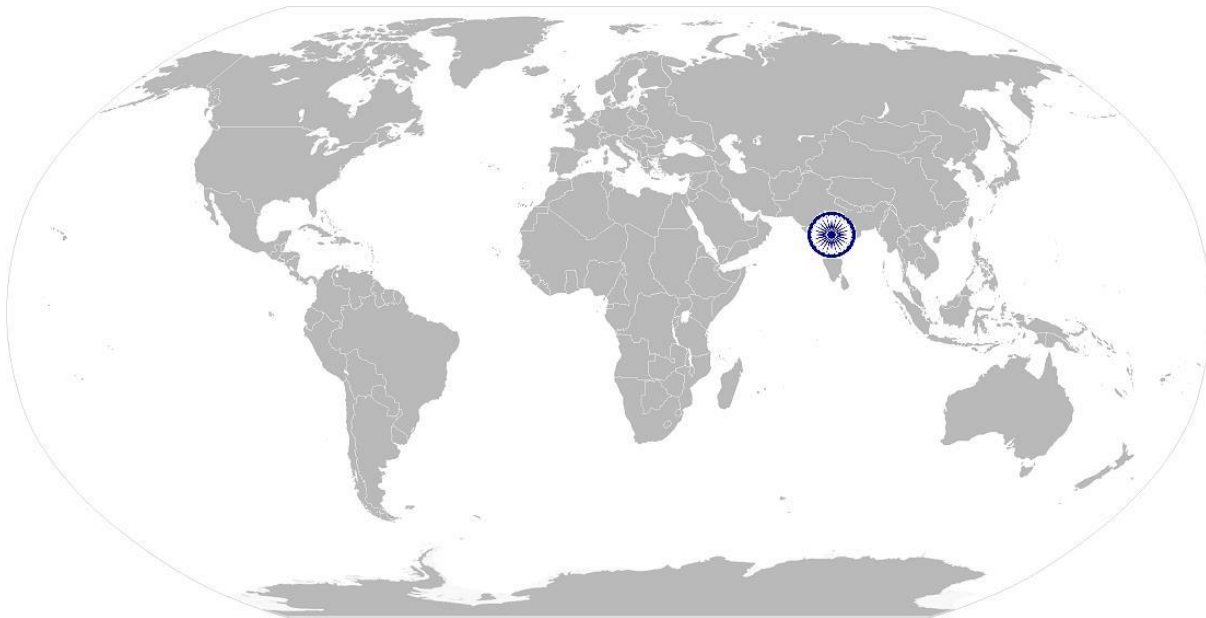
<p><b>B. Technical Knowledge</b></p>	<p>The user/individual on the job needs to know and understand:</p> <p>KB1. different types of breaches in health, safety and security and how and when to report these</p> <p>KB2. evacuation procedures for works and visitors</p> <p>KB3. how to summon medical assistance and the emergency services, where necessary</p> <p>KB4. how to use the health, safety and accident reporting procedures and the importance of these</p> <p>KB5. Disposal practices for hazardous chemicals</p> <p>KB6. government agencies in the area of safety, health and security and their norms and services</p>
<p><b>Skills (S) [Optional]</b></p>	
<p><b>A. Core Skills/ Generic Skills</b></p>	<p><b>Writing Skills</b></p> <p>The user/individual on the job needs to know and understand how to:</p> <p>SA1. complete accurate well-written work with attention to detail</p> <p><b>Reading Skills</b></p> <p>The user/individual on the job needs to know and understand how to:</p> <p>SA2. read instructions, guidelines, procedures rules and service level agreements</p> <p><b>Oral Communication (Listening and Speaking Skills)</b></p> <p>The user/individual on the job needs to know and understand how to:</p> <p>SA3. listen effectively and orally communicate information accurately</p>
<p><b>B. Professional Skills</b></p>	<p><b>Decision Making</b></p> <p>The user/individual on the job needs to know and understand how to:</p> <p>SB1. make decisions on suitable course location</p> <p><b>Plan and Organize</b></p> <p>The user/individual on the job needs to know and understand how to:</p> <p>SB2. plan and organize your work to meet health, safety and security requirements</p> <p><b>Customer Centricity</b></p> <p>Not applicable</p> <p><b>Problem Solving</b></p> <p>The user/ individual on the job needs to know and understand how to:</p> <p>SB3. apply problem solving approaches in different situations</p> <p><b>Analytical Thinking</b></p> <p>The user/individual on the job needs to know and understand how to:</p> <p>SB4. analyze data and activities</p> <p><b>Critical Thinking</b></p> <p>The user/individual on the job needs to know and understand how to:</p> <p>SB5. apply balanced judgments to different situations</p> <p>SB6. apply, analyze and evaluate the information gathered from observation, experience, reasoning or communication, as guide to thought and action</p>

TEL/N2509

Health and Safety

## NOS Version Control

NOS Code	TEL/N2509		
Credits (NSQF)	TBD	Version number	1.0
Industry	Telecom	Drafted on	14/06/2017
Industry Sub-sector	Handset	Last reviewed on	10/11/2017
Occupation	Communication Electronics	Next review date	10/11/2021



Qualification Pack – Telecom Surface Mount Technology (SMT) Technician

Annexure

**Nomenclature for QP and NOS**

**Qualifications Pack**

[ABC]/ Q2501

9 characters

[Insert 3 letter code for SSC]

Q denoting Qualifications Pack

QP number (2 numbers)

Occupation (2 numbers)

**Occupational Standard**

An example of NOS with 'N'  
[ABC] / N 2501

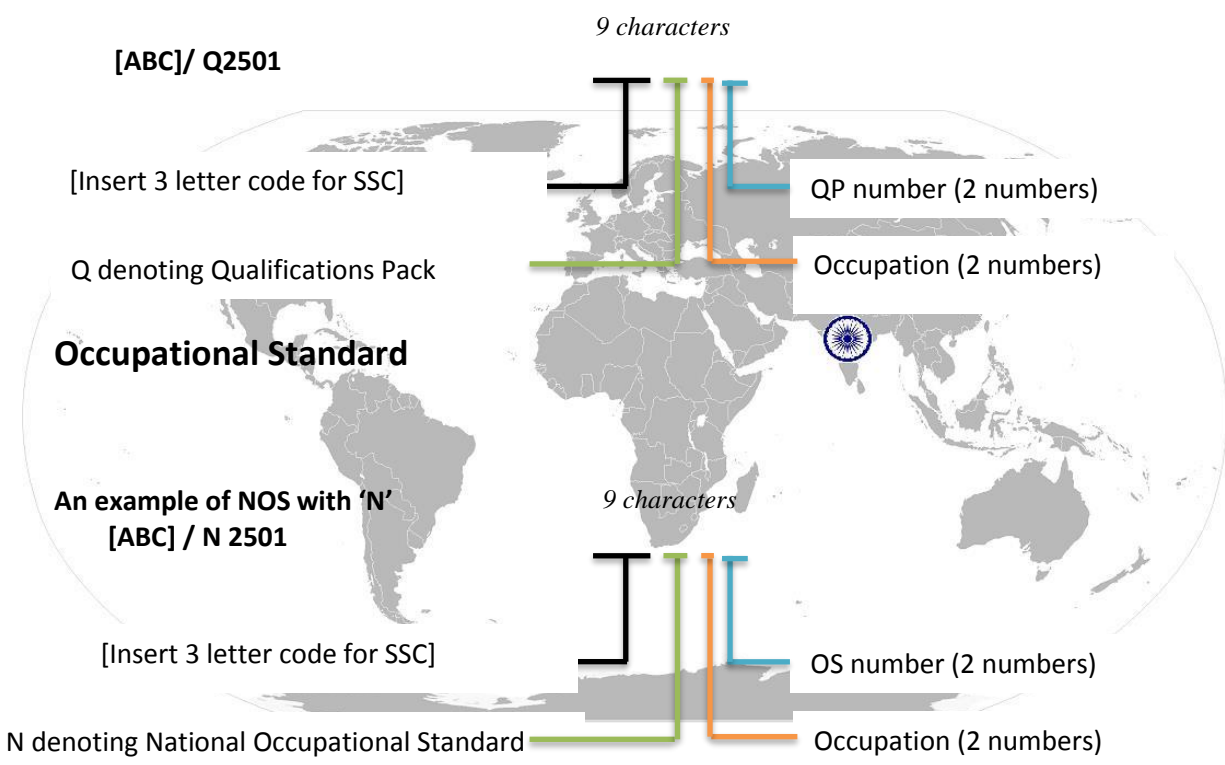
9 characters

[Insert 3 letter code for SSC]

N denoting National Occupational Standard

OS number (2 numbers)

Occupation (2 numbers)



*Qualification Pack – Telecom Surface Mount Technology (SMT) Technician*

The following acronyms/codes have been used in the nomenclature above:

Sub-sector	Range of Occupation numbers
Service	01- 20
Handset	21 – 40
Passive Infra	41 – 60
Network managed	61 – 80

Sequence	Description	Example
Three letters	Industry name	TEL
Slash	/	/
Next letter	Whether QP or NOS	Q
Next two numbers	Occupation code	01
Next two numbers	OS number	01

*Qualification Pack – Telecom Surface Mount Technology (SMT) Technician*

**CRITERIA FOR ASSESSMENT OF TRAINEES**

**Job Role** : Telecom Surface Mount Technology Technician  
**Qualification Pack** : TEL/Q2501  
**Sector Skill Council** : Telecom Sector Skill Council

1. Criteria for assessment for each Qualification Pack will be created by the Sector Skill Council. Each Performance Criteria (PC) will be assigned marks proportional to its importance in NOS. SSC will also lay down proportion of marks for Theory and Skills Practical for each PC.
2. The assessment for the theory part will be based on knowledge bank of questions created by the SSC.
3. Assessment will be conducted for all compulsory NOS, and where applicable, on the selected elective/option NOS/ set of NOS.
4. Individual assessment agencies will create unique question papers for theory and skill practical part for each candidate at each examination/ training center.
5. To pass the Qualification Pack, every trainee should score a minimum 70% of aggregate marks to successfully clear the assessment.
6. In case of unsuccessful completion, the trainee may seek re-assessment on the Qualification Pack.

<b>Compulsory NOS</b>			<b>Total Marks: 400</b>		<b>Marks Allocation</b>	
<b>Assessable Outcomes</b>	<b>Assessment criteria for outcomes</b>	<b>Total Marks (400)</b>	<b>Out of</b>	<b>Theory</b>	<b>Skills Practical</b>	
TEL/N2503 Baking of boards	PC1. ascertain the baking requirements as per the customer specifications or standard processes	100	8	5	3	
	PC2. demonstrate proper stacking/ placement of boards in the oven rack		9	4	5	
	PC3. demonstrate setting of temperature and timer of the oven as per the requirement		14	5	9	
Screen printing process	PC4. select correct tools and accessories (stencil matching the part/ pattern number vis-à-vis the PCB for screen printing, squeegee as per PCB size, correct solder paste/ combination as per the specifications)		12	4	8	
	PC5. demonstrate proper cleaning of the stencil, before and after use, using the specified process and solvents		8	2	6	
	PC6. demonstrate process for even deposition of paste on boards		9	3	6	
	PC7. demonstrate process of properly thawing the solder pastes and setting of solder paste parameters as per the specifications		14	5	9	
	PC8. demonstrate correct positioning of stencil, solder paste & squeeze and related parameters in the screen printer and undertake screen printing operation		12	4	8	
	PC9. carry out paste thickness measurement as part of post printing process and check the thickness for conformance to the specification		14	3	11	
	<b>Total</b>	<b>100</b>	<b>100</b>	<b>35</b>	<b>65</b>	

*Qualification Pack – Telecom Surface Mount Technology (SMT) Technician*

TEL/N2504 Feeding placement data	PC1. read specifications of board and map to the correct software version of chip shooter/ pitch placer	100	5	0	5
	PC2. read and interpret Gerber data, x-y coordinate data		5	0	5
	PC3. work with user interface and features of the machine/ equipment software and demonstrate the same		6	3	3
	PC4. demonstrate data entry/ loading of component placement program to the chip shooter/ fine pitch placer		6	4	2
Loading of chip component rolls	PC5. check operation of the roll feeder mechanism		4	1	3
	PC6. feed Gerber data and insert feeder rolls on the suggested slots of the chip shooter		4	2	2
	PC7. verify component rolls as per the Part number/ work specification		7	2	5
	PC8. demonstrate loading of chip component rolls in the feeder		6	2	4
	PC9. demonstrate manual data entry of X-Y co-ordinates		5	2	3
Loading of chip component trays	PC10. load components on the tray as per the placement program		5	2	3
	PC11. place the components with correct orientation in the feeder tray		6	2	4
	PC12. check operation of the mechanism including vision cameras		7	1	6
Operating chip shooter and fine pitch placer and functional/ QA checks on the PCB	PC13. verify correct loading of boards, program and component rolls/ trays		6	2	4
	PC14. check placement vacuum pressure		4	2	2
	PC15. check for feeder mechanism functions and ensure its error free operation		6	0	6
	PC 16. operate the component placement equipment		5	2	3
	PC17. use tape board technique to verify the placement accuracy		7	2	5
	PC18. verify the correctness of components and placement (under microscope) for the first sample board		6	4	2
	<b>Total</b>	<b>100</b>	<b>100</b>	<b>33</b>	<b>67</b>
TEL/N2505 Preparing the re-flow machine	PC1. interpret solder paste parameters from the datasheet and suggested parameters from re-flow machine	100	12	5	7
	PC2. demonstrate loading of parameters in the re-flow machine		10	4	6



*Qualification Pack – Telecom Surface Mount Technology (SMT) Technician*

	PC3. demonstrate passing a sample PCB through the re-flow machine, with reading being recorded using thermal probes		16	8	8
	PC4. match the readings with the desired outcome and undertake corrective settings		12	4	8
Re-flow operation on the PCB and its QA checks	PC5. undertake setting of machines is set as per the parameters as ascertained during the preparatory process		10	5	5
	PC6. prepare and pass the loaded PCB (with solder and components placed) through the re-flow machine		14	7	7
	PC7. safely remove the PCB at the end of the cycle		12	4	8
	PC8. check for any dry solder, ascertain even reflow, tombstone, de-lamination, mis-alignment and/ or disturbed components and any other damage to PCB		14	6	8
	<b>TOTAL</b>	<b>100</b>	<b>100</b>	<b>43</b>	<b>57</b>
TEL/N2502 Cleaning of telecom boards	PC1. demonstrate ability to clean the board from flux residues, white patches and/ or powder, using correct and specified solvent	100	15	5	10
	PC2. operate vapour de-greaser (boil, rinse, vapourise and dry) to clean the boards		15	7	8
	PC3. demonstrate safe packaging and storage of telecom boards, using the specified wrapping material		15	4	11
Inspection - QA/QC	PC4. demonstrate ability to check telecom boards for any missing components, wrongly mounted components (location, value) or improper placement, vis-à-vis the specifications		12	7	5
	PC5. demonstrate ability to check the telecom boards for soldering workmanship and defects, proper placement of board identifier, adherence to specifications, conformal coatings		13	6	7
	PC6. demonstrate complaint handling and escalation processes		15	8	7
	PC7. undertake checks of shop floor with respect to adherence to the processes and parameters (temperature, humidity)		15	7	8
	<b>Total</b>	<b>100</b>	<b>100</b>	<b>44</b>	<b>56</b>
TEL/N2509 Health & safety compliance and emergency procedures	PC1. ensure that work is carried out in accordance with the laid down safety, security policies and procedures of the organization	100	10	6	4
	PC2. ensure that site is assessed for safety and emergency readiness compliance as per company's guidelines		12	6	6
	PC3. ensure electrical safety compliances and EMI/EMC hygiene requirements are met as per the guidelines		15	9	6

Qualification Pack – Telecom Surface Mount Technology (SMT) Technician

PC4. identify and correct any hazards that you can deal with safely, competently and within the limits of your authority		15	10	5
PC5. report any hazards that you are not competent to deal with to the relevant person in line with organizational procedures and warn other people who may be affected		12	7	5
PC6. follow your organizations 's emergency procedures promptly, calmly and efficiently		12	6	6
PC7. identify and recommend opportunities for improving health, safety, security to the designated person		14	8	6
PC8. complete any health and safety records legibly and accurately		10	5	5
<b>Total</b>	100	<b>100</b>	<b>57</b>	<b>43</b>